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User's Manual

IE-703040-MC-EM1

In-circuit Emulator Option Board

Target device V850/SV1™

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INTRODUCTION

Target Readers	This manual is intended for users who design and develop application systems using the V850/SV1 ^{TM} .		
Purpose	The purpose of this manual is to describe the proper operation of the IE-703040-MC- EM1 and its basic specifications.		
Organization	This manual is divided into the following parts.OverviewNames and functions of componentsCautions		
How to Read This Manual	It is assumed that the reader of this manual has general knowledge in the field electrical engineering, logic circuits, and microcontrollers. The IE-703040-MC-EM1 is used connected to the IE-703002-MC in-circuit emula This manual explains the basic setup procedure and switch settings of the 703002-MC when it is connected to the IE-703040-MC-EM1. For the names functions of parts, and the connection of elements, refer to the IE-703002-MC US Manual (U11595E) . To learn about the basic specifications and operation methods		
		nanual in the order of the CONTENTS . ration methods and command functions, etc., of the IE-703002-MC	
	and IE-703040-M		
Conventions		Footnote for item marked with Note in the text Information requiring particular attention Supplementary information ntation: Binary ··· xxxx or xxxxB Decimal ··· xxxx Hexadecimal ··· xxxxH he power of 2 (address space, memory capacity): K (kilo): 2 ¹⁰ = 1024	
Terminology	The meanings of	M (mega): $2^{20} = 1024^2$ terms used in this manual are listed below.	
	-		
	Target device Target system	The device that is targeted for emulation. The system (user-built system) that is targeted for debugging. This includes the target program and user-configured hardware.	

Related Documents

When using this manual, refer to the following manuals.

The related documents indicated in this publication may include preliminary versions. However, preliminary versions are not marked as such.

O Documents related to development tools (user's manuals)

Document	Document Number	
IE-703002-MC		U11595E
IE-703040-MC-EM1		This manual
CA830, CA850 (C Compiler package)	Operation Windows-based	U13998E
	C language	U13997E
	Project manager	U13996E
CA850 (C Compiler package)	Assembly Language	U13828E
ID850 (Ver.1.31) (Integrated debugger)	Operation Windows-based	U13716E
ID850 (Ver.2.00 or more) (Integrated debugger)	Operation Windows-based	U14217E
SM850 (Ver.2.00 or more) (System simulator)	Operation Windows-based	U13759E
RX850 (Real-time OS)	Basics	U13430E
	Installation	U13410E
RX850 Pro (Real-time OS)	Fundamental	U13773E
	Installation	U13774E
RD850 (Task debugger) ^{№00}	Windows-based	U11158E
RD850 (Ver.3.0) (Task debugger)	Windows-based	U13737E
RD850 Pro (Ver.3.0) (Task debugger)	Windows-based	U13916E
AZ850 (System performance analyzer)		U11181E

Note For ID850 (Ver. 1.31 only)

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CHAPTER 1 OVERVIEW

The IE-703040-MC-EM1 is an option board for the IE-703002-MC in-circuit emulator. By connecting the IE-703040-MC-EM1 and IE-703002-MC, hardware and software can be debugged efficiently in system development using the V850/SV1.

In this manual, the basic setup procedure and switch settings of the IE-703002-MC when using the IE-703040-MC-EM1 are described. For the names and functions of the parts of the IE-703002-MC, and for the connection of elements, refer to the **IE-703002-MC User's Manual (U11595E)**.

1.1 Hardware Configuration

Option board (IE-703040-MC-EM1)	By adding this board, the IE-703002-MC can be used as in-circuit emulator for V850/SV1.
	Optional hardware
Extension probe (SC-176SD ^{Note 1})	General-purpose extension probe made by TOKYO ELETECH CORPORATION
PC interface board IE-70000-xx-IF-B IE-70000-xx-IF-C IE-70000-PCI-IF IE-70000-CD-IF-A	This board is used to connect the IE-703002-MC to a personal computer. This board is inserted in the expansion slot of the personal computer. xx: 98 (for PC-9800 series C bus) ^{Note 2} PC (for IBM PC/AT [™] or compatibles ISA bus) ^{Note 2} IE-70000-PCI-IF: for PCI bus IE-70000-CD-IF-A: for PCMCIA socket
Network module (IE-70000-MC-SV3)	This module is used when a workstation controls the IE-703002-MC vi Ethernet [™] .

Notes 1. For further information, contact Daimaru Kogyo Co., Ltd. Tokyo Electronics Department (TEL +81-3-3820-7112) Osaka Electronics Department (TEL +81-6-6244-6672)

2. Cannot be used for PC98-NX series

1.2 Features (When Connected to IE-703002-MC)

- O Maximum operating frequency: 20 MHz (at 3.3 to 5.0-V operation)
- O Extremely lightweight and compact
- O Higher equivalence with target device can be achieved by omitting buffer between signal cables.
- O The following pins can be masked.
 - RESET, NMI, WAIT, HLDRQ
- O Two methods of connection to target system:
 - Pod tip direct connection (For information on the pod, refer to the IE-703002-MC User's Manual (U11595E))
 - Attach an extension probe (sold separately) to the pod tip for connection
- O The dimensions of the IE-703040-MC-EM1 are as follows.

Parameter		Value	
Power consumption (Max. value at 3.3-V supply voltage)		0.35 W (at 20-MHz operation frequency) ^{Note}	
External dimensions	Height	15 mm	
(Refer to APPENDIX PACKAGE DRAWINGS)	Length	194 mm	
DRAWINGS)	Width	96 mm	
Weight		160 g	

Note 10.35 W when IE-703002-MC connected to IE-703040-MC-EM1

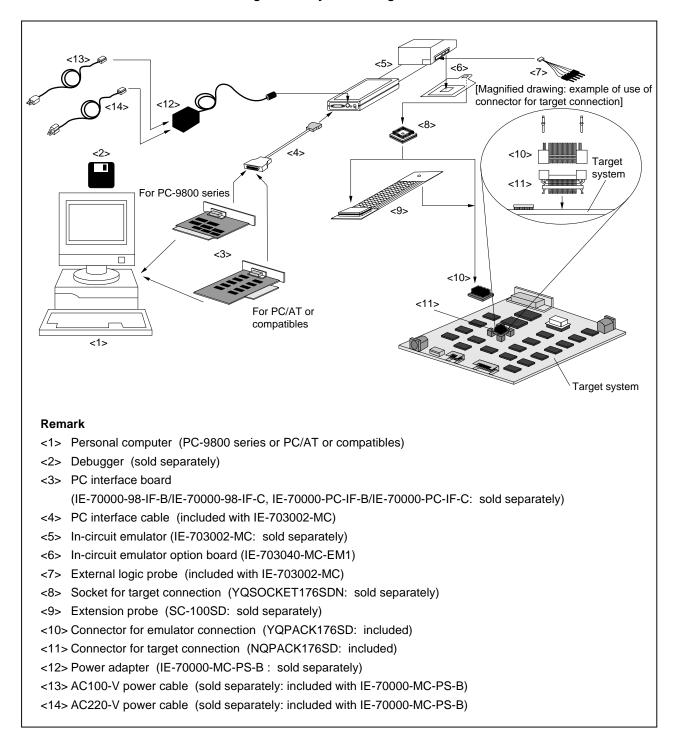
1.3 Function Specifications (When Connected to IE-703002-MC)

Parameter			Specification
Emulation memory capacity	Internal ROM		256 Kbytes
	External	In ROM-less mode	2 Mbytes
	memory	When using iROM	1 Mbyte
Coverage memory capacity for	Internal ROM		256 Kbytes
execution/pass detection	External	In ROM-less mode	2 Mbytes
	memory	When using iROM	1 Mbyte
Coverage memory capacity for memory access detection	External memory		1 Mbyte
Coverage memory capacity for	for Internal ROM		256 Kbytes
branching entry number counting	External	In ROM-less mode	2 Mbytes
	memory	When using iROM	1 Mbyte

Caution Some of the functions may not be supported, depending on the debugger used.

1.4 System Configuration

The system configuration when connecting the IE-703002-MC to the IE-703040-MC-EM1 and a personal computer (PC-9800 series or PC/AT[™] (or compatibles)) is shown below.





1.5 Contents in Carton

The carton of the IE-703040-MC-EM1 contains a main unit, guarantee card, packing list, and accessory bag. Make sure that the accessory bag contains this manual and the connector accessories. If there are missing or damaged items, please contact an NEC sales representative or an NEC distributor.

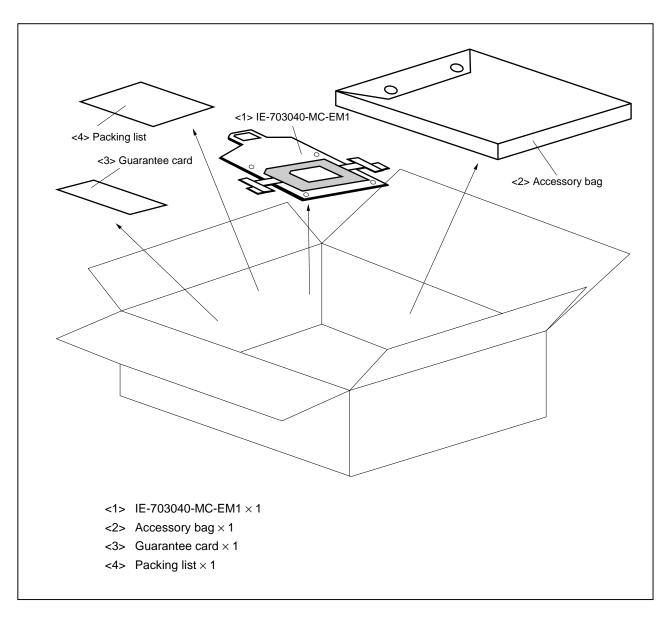
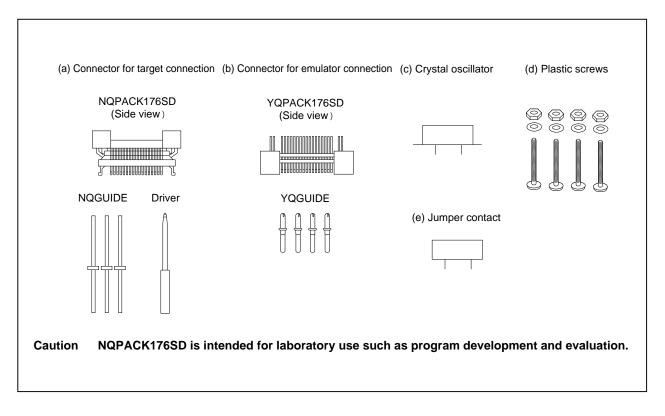


Figure 1-2. Contents in Carton

Check that the accessory bag contains this manual, an accessory list (\times 1), and the following accessories.

- (a) Connector for target connection (NQPACK176SD) \times 1 (including NQGUIDE \times 3, driver \times 1)
- (b) Connector for emulator connection (YQPACK176SD) \times 1 (including YQGUIDE \times 4)
- (c) Crystal oscillator (20-MHz, 8-pin type)
- (d) Plastic screws \times 4 (including nuts and washer \times 4)
- (e) Jumper contact $\times 1$

Figure 1-3. Accessories



1.6 Connection between IE-703002-MC and IE-703040-MC-EM1

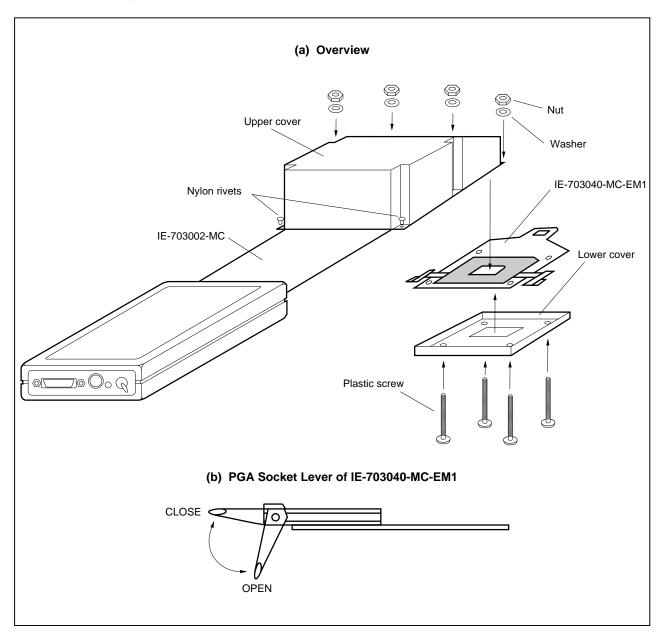
The procedure for connecting the IE-703002-MC and IE-703040-MC-EM1 is described below.

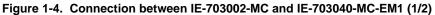
Caution Connect carefully so as not to break or bend connector pins.

- <1> Remove the pod cover (upper and lower) of the IE-703002-MC.
- <2> Replace the crystal oscillator mounted in the pod of the IE-703002-MC with the crystal oscillator supplied (20 MHz) or an arbitrary oscillator (user's frequency).
- <3> Set the PGA socket lever of the IE-703040-MC-EM1 to the OPEN position as shown in Figure 1-4 (b).
- <4> Connect the IE-703040-MC-EM1 to the PGA socket at the back of the IE-703002-MC pod (refer to Figure 1-4 (c)). When connecting, position the IE-703002-MC and IE-703040-MC-EM1 so that they are horizontal.
- <5> Set the PGA socket lever of the IE-703040-MC-EM1 to the CLOSE position as shown in Figure 1-4 (b).
- <6> Set the IE-703002-MC pod jumpers (JP1 to JP4). Open JP1 and JP3 (Remove the jumper contact and attach the removed jumper contact to one of the jumper pins to avoid losing it.)

Retain the factory settings of JP2 (pins 1 and 2 shorted, and pins 5 and 6 shorted). Short pins 2 and 3 of JP4.

- <7> Fix the IE-703040-MC-EM1 between the IE-703002-MC pod covers (upper and lower) with the plastic screws (supplied with the IE-703002-MC).
- <8> Fix the IE-703002-MC pod cover (upper) end with nylon rivets.
 - Remark For the JP1 setting, refer to 2.3 Illegal Access Detection ROM Setting. For JP3 and JP4, refer to 2.4 CPU Operation Voltage Range Switch Setting.





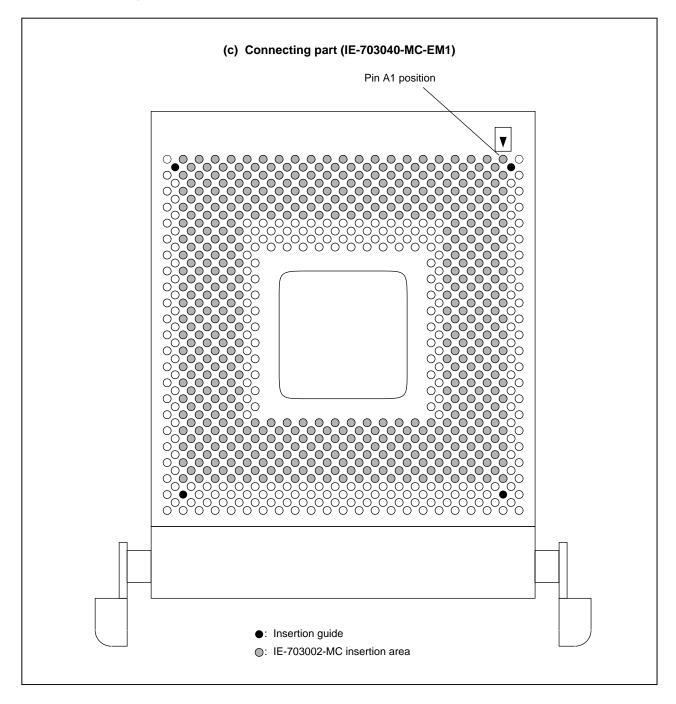


Figure 1-4. Connection between IE-703002-MC and IE-703040-MC-EM1 (2/2)

CHAPTER 2 NAMES AND FUNCTIONS OF COMPONENTS

This chapter describes the names, functions, and switch settings of components in the IE-703040-MC-EM1. For the details of the pod, jumper, and switch positions, etc., refer to the **IE-703002-MC User's Manual (U11595E)**.

2.1 Component Names and Functions of IE-703040-MC-EM1

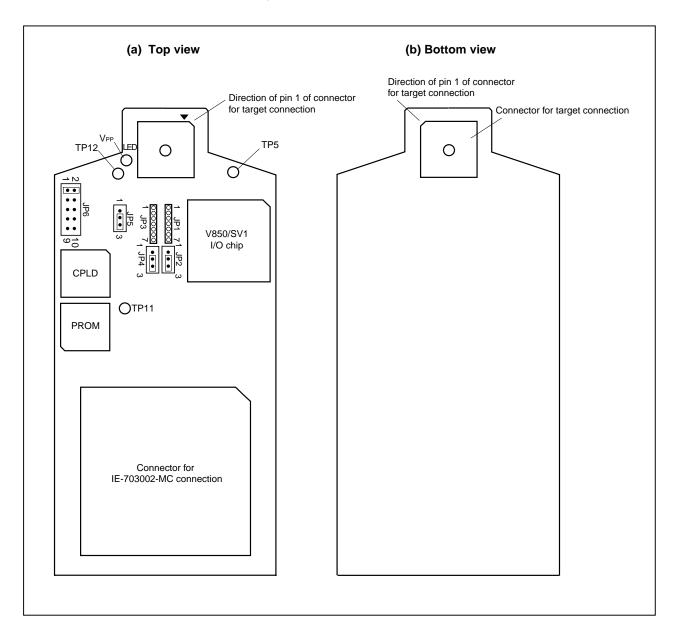


Figure 2-1. IE-703040-MC-EM1

(1) TEST pins (TP5, TP11, TP12)

These are pins used for testing the analog signals of the standalone emulator.

- TP 5: GND
- TP 11: GND
- TP 12: GND

(2) JP1

This is a pin board for product check. Mount nothing on JP1.

(3) JP2, JP4

These are pin boards for product check. Use and retain the factory settings (pins 2 and 3 shorted) (For details, refer to **2.2 Clock Settings**)

(4) JP3

This is a pin board for supplying the subsystem clock. (For details, refer to 2.2 Clock Settings)

(5) JP5

This is a jumper for switching the main system clock supply source.

(6) JP6

This is a pin board for product check. Use and retain the factory settings (pins 1 and 2 shorted).

(7) LED

LED for VPP ON: Voltage is applied to VPP OFF: Voltage is not applied to VPP

(8) Connector for IE-703002-MC connection

This is a connector for connecting with the IE-703002-MC.

(9) Connector for target connection

This is a connector for connecting with the target system or the extension probe.

2.2 Clock Settings

This section describes the clock settings.

For the position of the JP1 and JP2 in the IE-703040-MC-EM1, refer to Figure 2-1.

For the jumper switch position in the IE-703002-MC, refer to the IE-703002-MC User's Manual (U11595E).

2.2.1 Main system clock setting

Table 2-1.	Main	System	Clock Setting	
	main	Oystem	Clock Detting	

Emulator Use	Clock Supply Method IE-703040-MC-EM1 Setting IE-70300		03002-MC Setting		
Environment		JP1	SW1	SW2	JP2
When using emulator as standalone unit	Internal clock		ON	ON	7 8 9 1 2
When using emulator with target system	Internal clock				
	Target clock ^{Note}				

Note The target clock supports only an oscillator (X2 cannot be used because it is not connected in the emulator).

Clock input by resonator is not supported.

2.2.2 Subsystem clock setting

Emulator Use	Clock Supply Method	IE-703040-MC-EM1 Setting		
Environment		JP3		
When using emulator as standalone unit	Internal clock ^{Note 1}	Oscillator mounted (a 32.768-kHz oscillator is mounted when shipped) ^{Note 3}		
When using emulator with target system	Internal clock ^{Note 1}	Oscillator mounted (a 32.768-kHz oscillator is mounted when shipped) ^{Note 3}		
	Target clock ^{Note 2}	Pins 3 and 4 of JP3 are shorted ^{Note 4}		
		1 2 3 4 5 6 7 0 0 0 0 0 0 JP3		

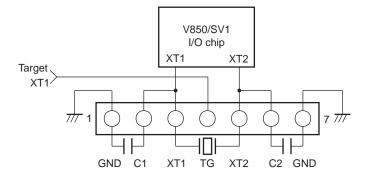
Table 2-2. Subsystem Clock Setting

- **Notes 1.** The internal clock does not support the clock input by an oscillator.
 - 2. The target clock supports only an oscillator (XT2 cannot be used because it is not connected in the emulator).

Clock input by oscillator is not supported.

3. To use a subsystem clock frequency other than 32.768 kHz, remove the clock module on JP3 and mount any oscillator.

The specifications of JP3 are as follows.

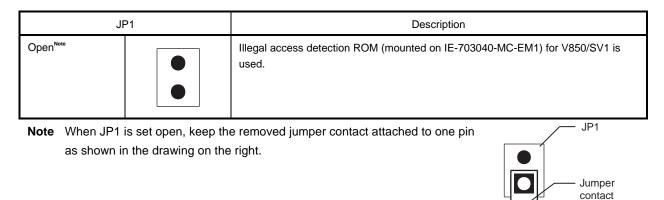


4. Prepare the short pin.

2.3 Illegal Access Detection ROM Setting

If using the IE-703002-MC for an in-circuit emulator for the V850/SV1 by connecting the IE-703040-MC-EM1, set JP1 of the IE-703002-MC as follows.

Table 2-3.	JP1	Setting	in	IE-703002-MC
------------	-----	---------	----	--------------



2.4 CPU Operation Voltage Range Switching Setting

If using the IE-703002-MC for an in-circuit emulator for the V850/SV1 by connecting the IE-703040-MC-EM1, set JP3 and JP4 of the IE-703002-MC as follows.

JP3,	, JP4	Description				
JP3		The operation voltage range of the IE-703002-MC is to 2 to 3.6 V				
JP4		The operation voltage range of the target system is 2 to 4.5 V. (Use this setting since the operation voltage range of the V850/SV1 is 2 to 3.6 V.)				

Table 2-4. JP3 and JP4 Setting in IE-703002-MC

Caution By settings of JP3, JP4 above, when the power supply of the target system is on, the IE-703002-MC operates at the same voltage as the target system. The IE-703002-MC always operates at 3.3 V when the power supply of the target system is off and using emulator as standalone unit.

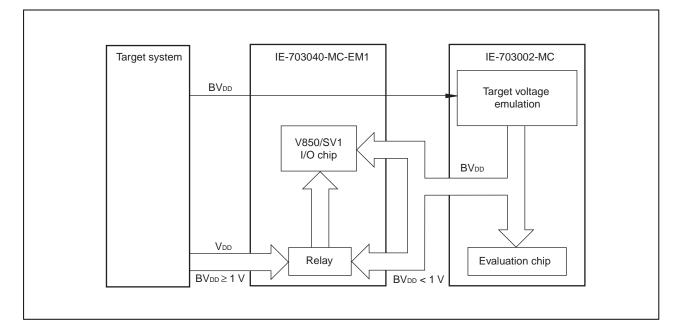
CHAPTER 3 FACTORY SETTINGS

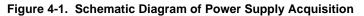
ltem	Description	Remark				
JP1	Oscillator not mounted	Pin board for product check				
JP2		Jumper switch for product check				
JP3	Oscillator mounted	32.768-kHz clock supplied for subsystem clock				
JP4		Jumper switch for product check				
JP5		Internal clock used for main system clock				
JP6	$\begin{array}{c} 2 \\ 1 \\ \end{array} \begin{array}{c} \bullet \bullet \bullet \bullet \bullet \\ \bullet \bullet \bullet \bullet \bullet \end{array} \begin{array}{c} 10 \\ 9 \\ \end{array}$	Jumper switch for product check				

CHAPTER 4 CAUTIONS

4.1 VDD and BVDD of Target System

- (1) BVDD in the target system is not connected to BVDD in the evaluation chip in the IE-703002-MC. The IE-703002-MC uses BVDD of the target system for the following purposes:
 - Power ON/OFF detection of target system
 - BVDD emulation of target system
- (2) When the voltage of the target system is 1 V or higher, the evaluation chip in the emulator operates using the supply of V_{DD} from the target system. The power consumption is equivalent to that of the V850/SV1.
- (3) When the voltage of the target system is lower than 1 V, the emulator recognizes the target system power is off and operates at 3.3 V.





4.2 NMI Signal

The input signal (NMI signal) from the target system is delayed ($t_{pD} = 0.25$ ns (TYP.)) because it passes through QS3125 (Q switch) before it is input to the I/O chip of the emulator.

In addition, the DC characteristics change. The input voltage becomes V_{IH} = 2.0 V (MIN.), V_{IL} = 0.8 V (MAX.), and the input current becomes I_{IN} = $\pm 0.5 \mu$ A (MAX.).

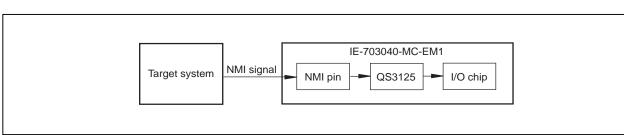
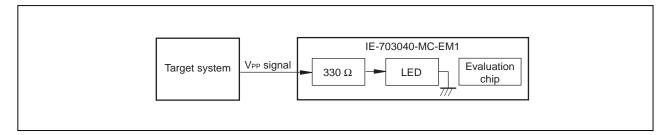


Figure 4-2. NMI Signal Flow Path

4.3 VPP Signal

The VPP signal from the target system is connected to LED via a 330- Ω resistor in the emulator. It is not connected to the evaluation chip in the emulator.





4.4 NMI Signal Mask Function

When using the P00/NMI pin in the port mode, do not mask the NMI signal.

4.5 Bus Interface Pin

The operation of the pin for the bus interface differs between the emulator and the target device as follows.

Pin Name		Internal Memory									External Memory			
	Memory Used by Emulator		Internal ROM	Internal RAM		Internal Peripheral I/O		Emulation RAM		Target System				
	F	R	W	R	R	W	R	W	R	W	R	W		
A16 to A21	Hold the	e last acce	essed add	dress					Active		Active			
AD0 to AD15	Hi-Z								Active		Active	Active		
ASTB	н	Н							Active		Active			
R/W	н	Н							Active		Active			
DSTB	Н	Н						Н		Active				
LBEN	Н	Н							Active		Active			
UBEN	Н	Н							Active		Active			
WAIT	Invalid	Invalid							Maskable		Maskable			
HLDRQ	Maskab	Maskable							Maskable		Maskable			
HLDAK	H or L	H or L							H or L		H or L			
WRL	н	н					н		н	Note				
WRH	н	н						н		Н	Note			
RD	н	Н							н		Note	Н		

Table 4-1. Bus Interface Pin Operation List (1/2)(a) During break

Note Active

Remarks 1. F: Fetch

- R: Read
- W: Write
- 2. H: High-level output
 - L: Low-level output
 - Hi-Z: High-impedance

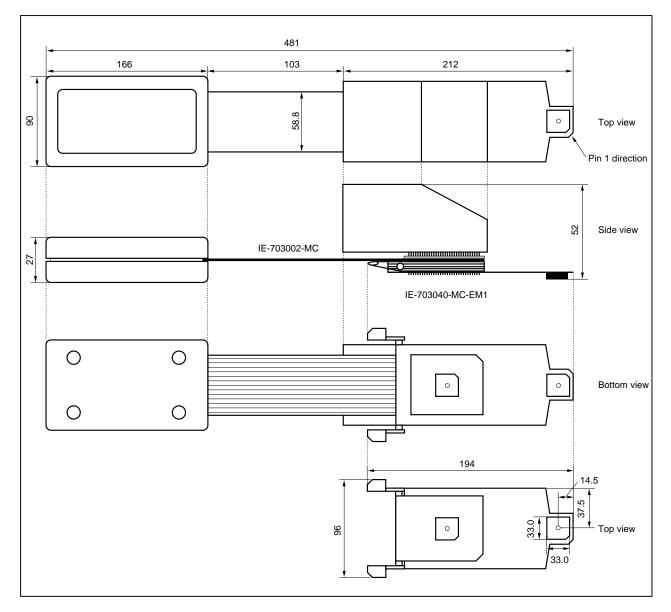
Pin	Internal Memory						External Memory						
Name	Interna	I ROM	In	ternal RA	Μ		ernal eral I/O	Emulation RAM F R W		Tai	Target System		
	F	R	F	R	W	R	W			F	R	W	
A16 to A21	Hold the last accessed address						Active Active						
AD0 to AD15	Hi-Z						Active			Active			
ASTB	н						Active			Active			
R/W	н							Active			Active		
DSTB	Н						H A			Active	Active		
LBEN	н						Active			Active			
UBEN	Н							Active			Active		
WAIT	Invalid							Maskable			Maskable		
HLDRQ	Maskab	Maskable						Maskable			Maskable		
HLDAK	H or L						H or L		H or L				
WRL	н						н		н		Note		
WRH	Н						Н			H Note		Note	
RD	н	Н						н			Note		Н

Table 4-1. Bus Interface Pin Operation List (2/2) (b) During run

Note Active

- Remarks 1. F: Fetch
 - R: Read
 - W: Write
 - 2. H: High-level output
 - L: Low-level output
 - Hi-Z: High-impedance

APPENDIX PACKAGE DRAWINGS



IE-703002-MC + IE-703040-MC-EM1 (Unit: mm)

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